



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD50N04S3-08	Issued	11. April 2021
MA#	MA001795118		
Package	PG-TO252-3-11	Weight*	371.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.269	0.61	0.61	6114	6114
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		580	
	non noble metal	copper	7440-50-8	215.017	57.92	58.00	579393	580147
wire	non noble metal	aluminium	7429-90-5	2.920	0.79	0.79	7868	7868
encapsulation	inorganic material	zinc oxide	1314-13-2	1.253	0.34		3377	
	miscellaneous	miscellaneous	-	6.266	1.69		16885	
	plastics	epoxy resin	-	18.798	5.07		50654	
	inorganic material	silicon dioxide	60676-86-0	99.004	26.68	33.78	266780	337696
lead finish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10078	10078
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.045	0.01		122	
	noble metal	silver	7440-22-4	0.057	0.02		153	
	non noble metal	lead	7439-92-1	2.164	0.58	0.61	5832	6107
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51676	51744
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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